

## **LM4881 Boomer® Audio Power Amplifier Series Dual 200 mW Headphone Amplifier with Shutdown Mode**

Check for Samples: [LM4881](#)

### **FEATURES**

- **VSSOP Surface Mount Packaging**
- **Unity-gain Stable**
- **External Gain Configuration Capability**
- **Thermal Shutdown Protection Circuitry**
- **No Bootstrap Capacitors, or Snubber Circuits are Necessary**

### **APPLICATIONS**

- **Headphone Amplifier**
- **Personal Computers**
- **Microphone Preamplifier**

### **KEY SPECIFICATIONS**

- **THD+N at 1kHz at 125mW continuous average output power into 8Ω 0.1% (max)**
- **THD+N at 1kHz at 75mW continuous 0.02% (typ)**
- **Output power at 10% THD+N at 1kHz into 8Ω 300 mW (typ)**
- **Shutdown Current 0.7μA (typ)**
- **Supply voltage range 2.7V to 5.5 V**

### **DESCRIPTION**

The LM4881 is a dual audio power amplifier capable of delivering 200mW of continuous average power into an 8Ω load with 0.1% THD+N from a 5V power supply.

Boomer™ audio power amplifiers were designed specifically to provide high quality output power with a minimal amount of external components using surface mount packaging. Since the LM4881 does not require bootstrap capacitors or snubber networks, it is optimally suited for low-power portable systems.

The LM4881 features an externally controlled, low power consumption shutdown mode which is virtually clickless and popless, as well as an internal thermal shutdown protection mechanism.

The unity-gain stable LM4881 can be configured by external gain-setting resistors.

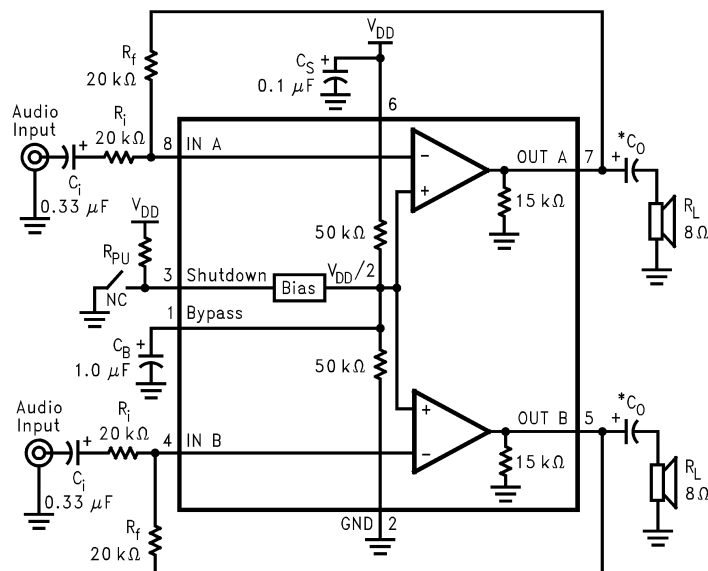


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Boomer is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

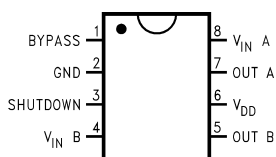
## Typical Application



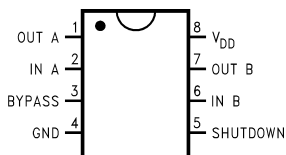
\*Refer to [Application Information](#) for information concerning proper selection of the input and output coupling capacitors.

**Figure 1. Typical Audio Amplifier Application Circuit**

## Connection Diagrams



**Figure 2. VSSOP Package  
Top View  
See Package Number DGK0008A**



**Figure 3. SOIC and PDIP Package  
Top View  
See Package Number D0008A, or P0008E**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## Absolute Maximum Ratings<sup>(1)(2)</sup>

Supply Voltage			6.0V
Storage Temperature			–65°C to +150°C
Input Voltage			–0.3V to V <sub>DD</sub> + 0.3V
Power Dissipation <sup>(3)</sup>			Internally limited
ESD Susceptibility <sup>(4)</sup>			2000V
ESD Susceptibility <sup>(5)</sup>			200V
Junction Temperature			150°C
Soldering Information	Small Outline Package	Vapor Phase (60 seconds)	215°C
		Infrared (15 seconds)	220°C
Thermal Resistance		$\theta_{JC}$ (VSSOP)	56°C/W
		$\theta_{JA}$ (VSSOP)	210°C/W
		$\theta_{JC}$ (SOIC)	35°C/W
		$\theta_{JA}$ (SOIC)	170°C/W
		$\theta_{JC}$ (PDIP)	37°C/W
		$\theta_{JA}$ (PDIP)	107°C/W

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) The maximum power dissipation must be derated at elevated temperatures and is dictated by T<sub>JMAX</sub>,  $\theta_{JA}$ , and the ambient temperature T<sub>A</sub>. The maximum allowable power dissipation is P<sub>DMAX</sub> = (T<sub>JMAX</sub> – T<sub>A</sub>) /  $\theta_{JA}$ . For the LM4881, T<sub>JMAX</sub> = 150°C, and the typical junction-to-ambient thermal resistance, when board mounted, is 210°C/W for the VSSOP Package and 107°C/W for package P0008E.
- (4) Human body model, 100 pF discharged through a 1.5 k $\Omega$  resistor.
- (5) Machine Model, 220 pF–240 pF discharged through all pins.

## Operating Ratings

Temperature Range T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub>	–40°C ≤ T <sub>A</sub> ≤ 85°C
Supply Voltage	2.7V ≤ V <sub>DD</sub> ≤ 5.5V

## Electrical Characteristics<sup>(1)(2)</sup>

The following specifications apply for V<sub>DD</sub> = 5V unless otherwise specified. Limits apply for T<sub>A</sub> = 25°C.

Symbol	Parameter	Conditions	LM4881		Units (Limits)
			Typ <sup>(3)</sup>	Limit <sup>(4)</sup>	
V <sub>DD</sub>	Power Supply Voltage			2.7	V (min)
				5.5	V (max)
I <sub>DD</sub>	Quiescent Current	V <sub>IN</sub> = 0V, I <sub>O</sub> = 0A	3.6	6.0	mA (max)
I <sub>SD</sub>	Shutdown Current	V <sub>PIN1</sub> = V <sub>DD</sub>	0.7	5	μA (max)
V <sub>OS</sub>	Offset Voltage	V <sub>IN</sub> = 0V	5	50	mV (max)

- (1) All voltages are measured with respect to the ground pin, unless otherwise specified.
- (2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. Electrical Characteristics state DC and AC electrical specifications under particular test conditions which ensure specific performance limits. This assumes that the device is within the Operating Ratings. Specifications are not ensured for parameters where no limit is given, however, the typical value is a good indication of device performance.
- (3) Typicals are measured at 25°C and represent the parametric norm.
- (4) Limits are specified to TI's AOQL (Average Outgoing Quality Level).

## Electrical Characteristics<sup>(1)(2)</sup> (continued)

The following specifications apply for  $V_{DD} = 5V$  unless otherwise specified. Limits apply for  $T_A = 25^\circ C$ .

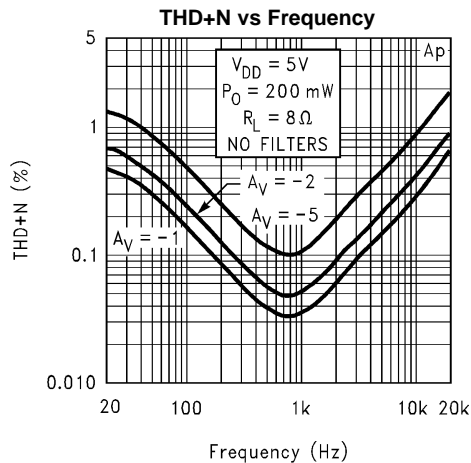
Symbol	Parameter	Conditions	LM4881		Units (Limits)
			Typ <sup>(3)</sup>	Limit <sup>(4)</sup>	
$P_O$	Output Power	THD = 0.1% (max); $f = 1\text{ kHz}$ ; $R_L = 8\Omega$	200	125	mW (min)
		$R_L = 16\Omega$	150		mW
		$R_L = 32\Omega$	85		mW
		THD + N = 10%; $f = 1\text{ kHz}$ ; $R_L = 8\Omega$	300		mW
		$R_L = 16\Omega$	200		mW
		$R_L = 32\Omega$	110		mW
THD+N	Total Harmonic Distortion + Noise	$R_L = 16\Omega$ , $P_O = 120\text{ mWrms}$ ;	0.025		%
		$R_L = 32\Omega$ , $P_O = 75\text{ mWrms}$ ; $f = 1\text{ kHz}$	0.02		%
PSRR		$C_B = 1.0\text{ }\mu\text{F}$ , $V_{RIPPLE} = 200\text{ mVrms}$ , $f = 120\text{ Hz}$	50		dB
$I_{DD}$	Quiescent Current	$V_{IN} = 0V$ , $I_O = 0A$	1.1		mA
$I_{SD}$	Shutdown Current	$V_{PIN1} = V_{DD}$	0.7		$\mu A$
$V_{OS}$	Offset Voltage	$V_{IN} = 0V$	5		mV
$P_O$	Output Power	THD = 1% (max); $f = 1\text{ kHz}$ ; $R_L = 8\Omega$	70		mW
		$R_L = 16\Omega$	65		mW
		$R_L = 32\Omega$	30		mW
		THD + N = 10%; $f = 1\text{ kHz}$ ; $R_L = 8\Omega$	95		mW
		$R_L = 16\Omega$	65		mW
		$R_L = 32\Omega$	35		mW
THD+N	Total Harmonic Distortion + Noise	$R_L = 16\Omega$ , $P_O = 60\text{ mWrms}$ ;	0.2		%
		$R_L = 32\Omega$ , $P_O = 25\text{ mWrms}$ ; $f = 1\text{ kHz}$	0.03		%
PSRR	Power Supply Rejection Ratio	$C_B = 1.0\text{ }\mu\text{F}$ , $V_{RIPPLE} = 200\text{ mVrms}$ , $f = 100\text{ Hz}$	50		dB

## External Components Description

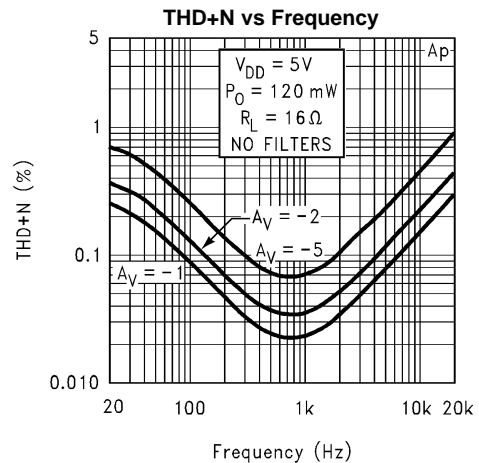
(Figure 1)

Components	Functional Description
1. $R_i$	Inverting input resistance which sets the closed-loop gain in conjunction with $R_f$ . This resistor also forms a high pass filter with $C_i$ at $f_c = 1 / (2\pi R_i C_i)$ .
2. $C_i$	Input coupling capacitor which blocks the DC voltage at the amplifier's input terminals. Also creates a highpass filter with $R_i$ at $f_c = 1 / (2\pi R_i C_i)$ . Refer to the section, <a href="#">Proper Selection of External Components</a> , for an explanation of how to determine the value of $C_i$ .
3. $R_f$	Feedback resistance which sets closed-loop gain in conjunction with $R_i$ .
4. $C_S$	Supply bypass capacitor which provides power supply filtering. Refer to the <a href="#">Application Information</a> section for proper placement and selection of the supply bypass capacitor.
5. $C_B$	Bypass pin capacitor which provides half-supply filtering. Refer to the section, <a href="#">Proper Selection of External Components</a> , for information concerning proper placement and selection of $C_B$ .
6. $C_O$	Output coupling capacitor which blocks the DC voltage at the amplifier's output. Forms a high pass filter with $R_L$ at $f_O = 1/(2\pi R_L C_O)$

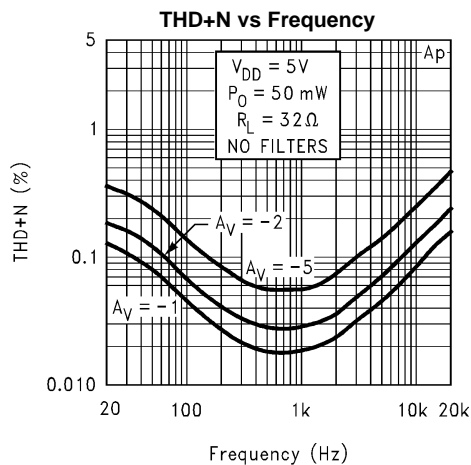
## Typical Performance Characteristics



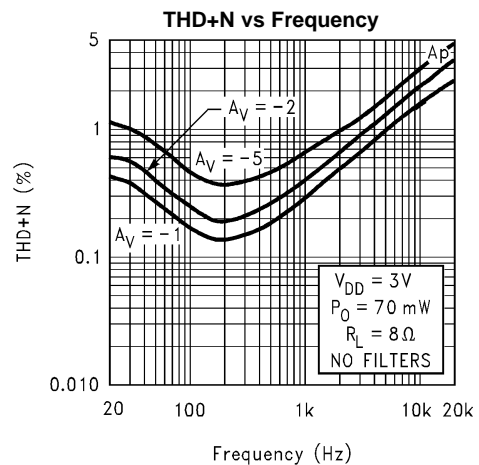
**Figure 4.**



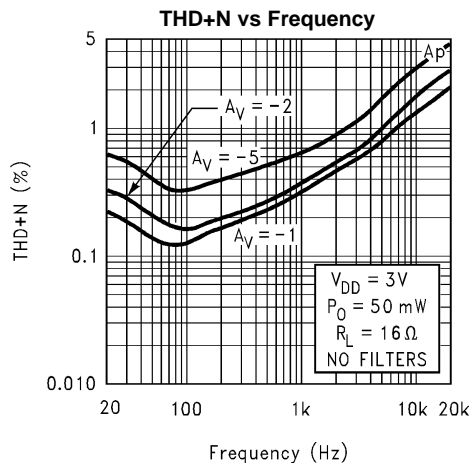
**Figure 5.**



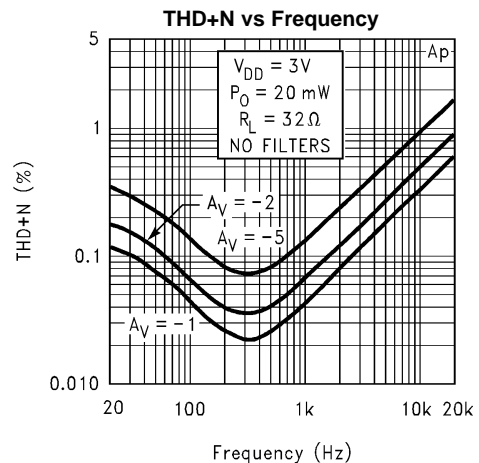
**Figure 6.**



**Figure 7.**



**Figure 8.**



**Figure 9.**

## Typical Performance Characteristics (continued)

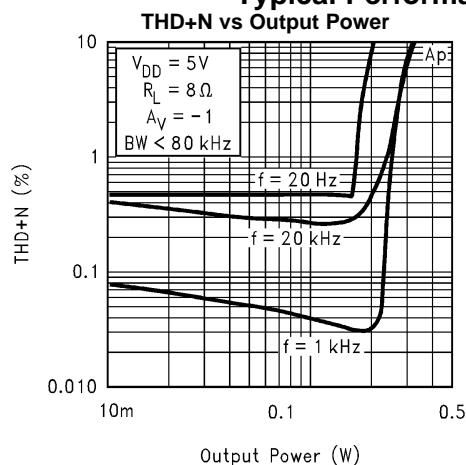


Figure 10.

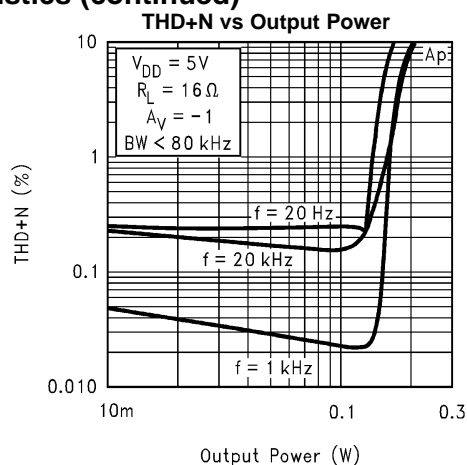


Figure 11.

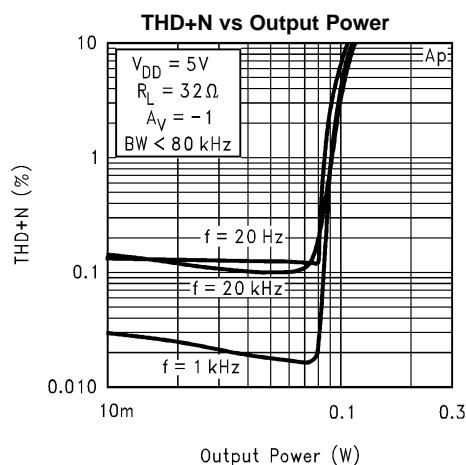


Figure 12.

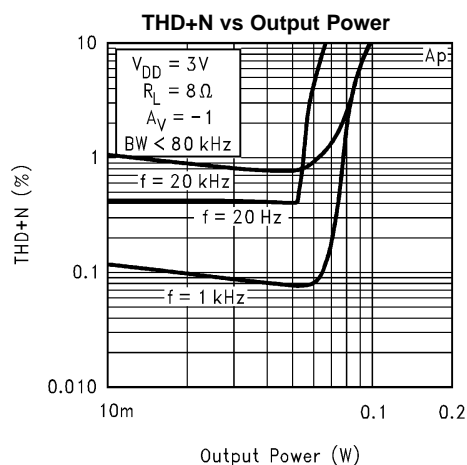


Figure 13.

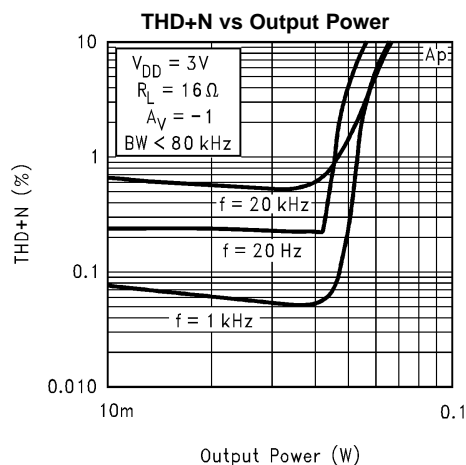


Figure 14.

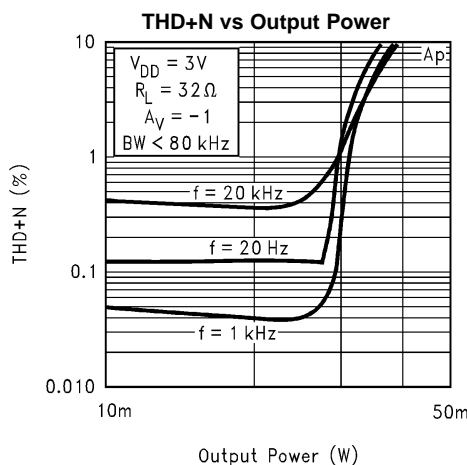


Figure 15.

## Typical Performance Characteristics (continued)

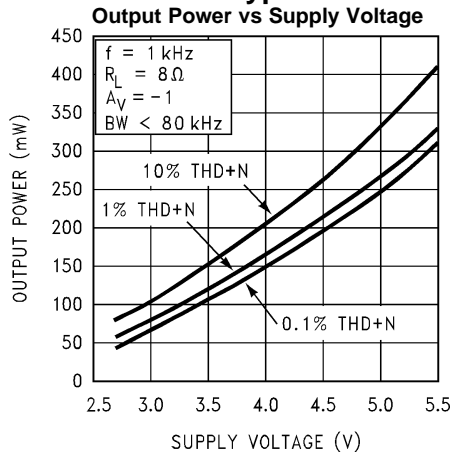


Figure 16.

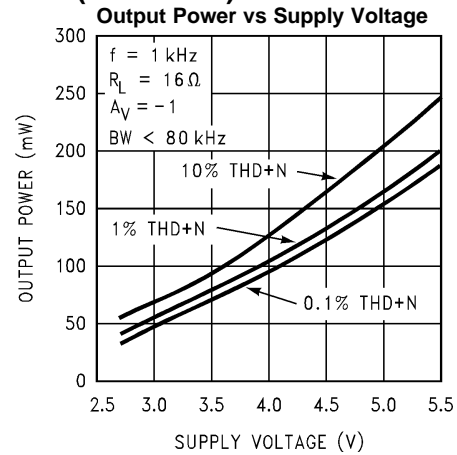


Figure 17.

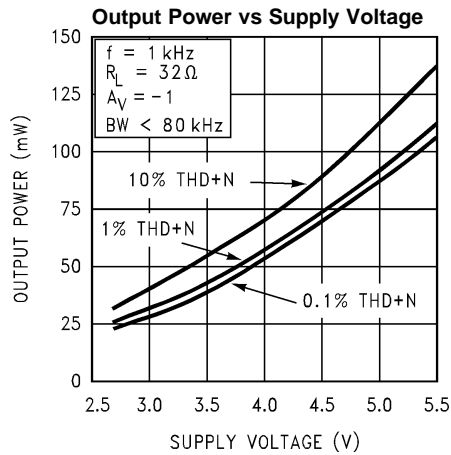


Figure 18.

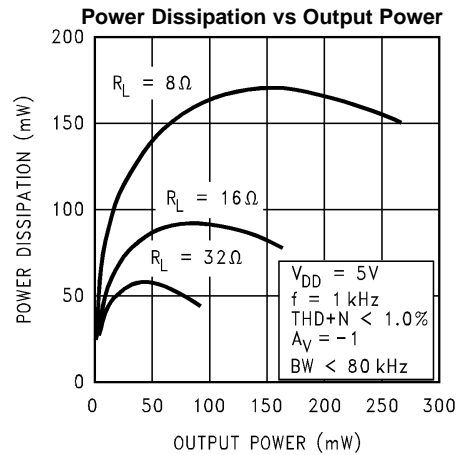


Figure 19.

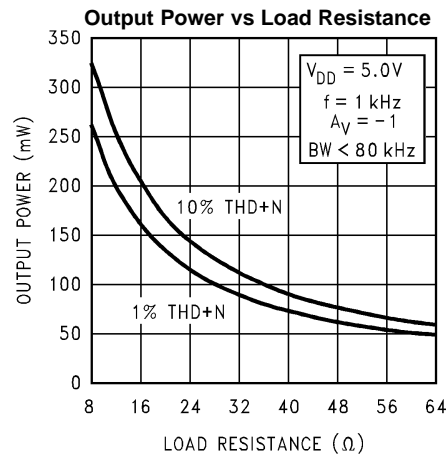


Figure 20.

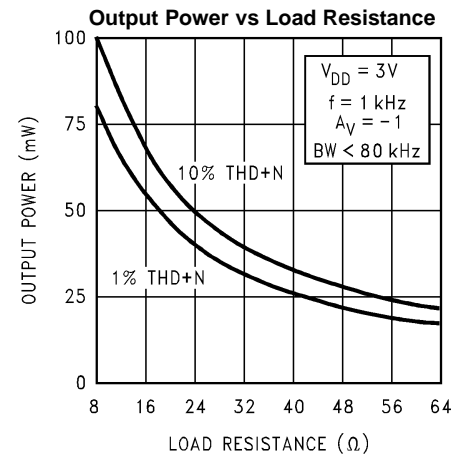


Figure 21.

## Typical Performance Characteristics (continued)

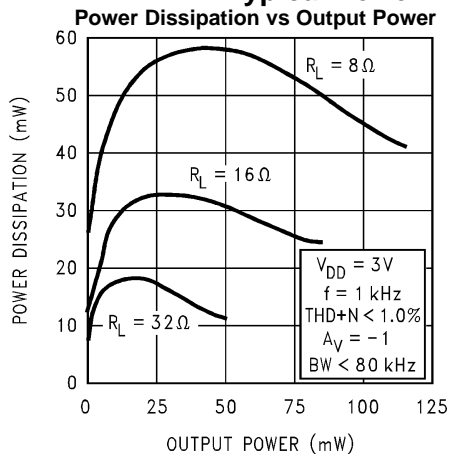


Figure 22.

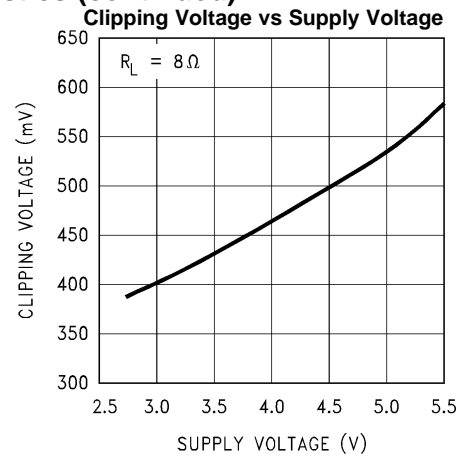


Figure 23.

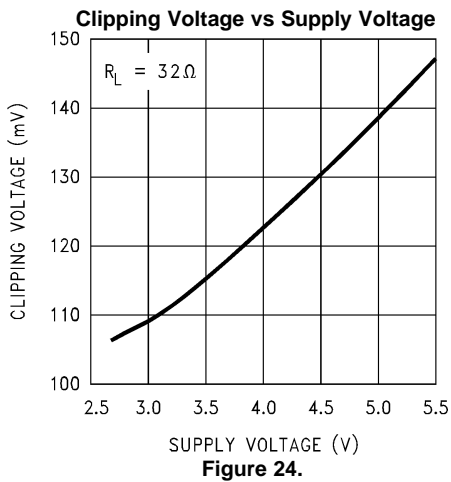


Figure 24.

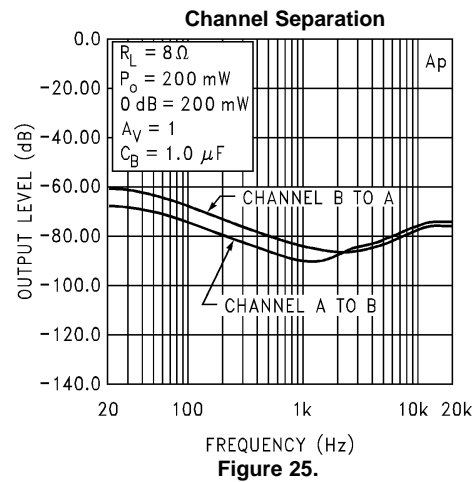


Figure 25.

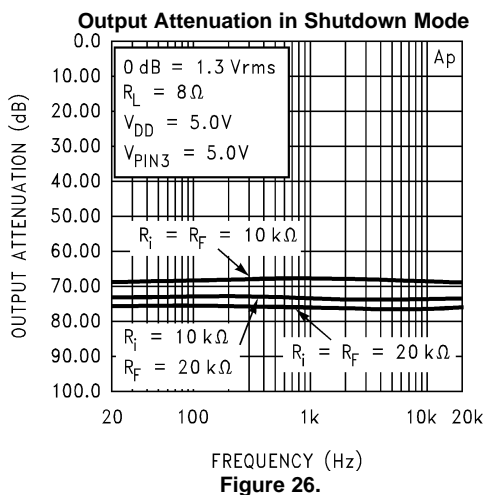


Figure 26.

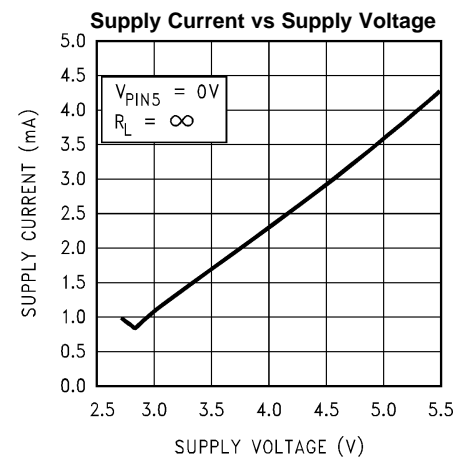


Figure 27.



## Typical Performance Characteristics (continued)

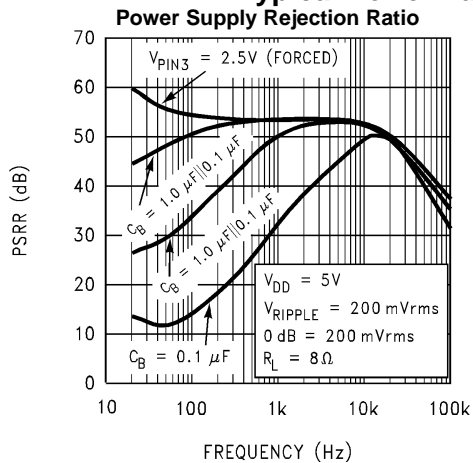


Figure 28.

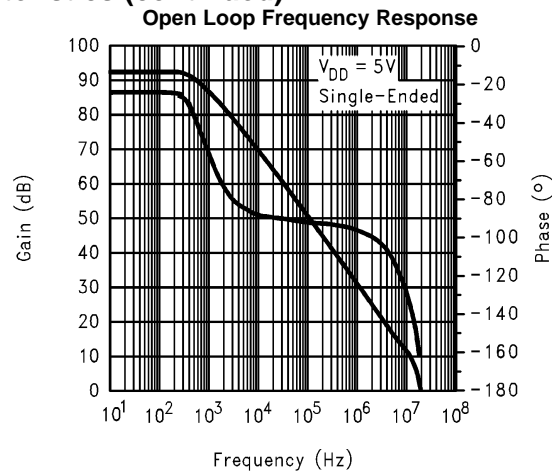


Figure 29.

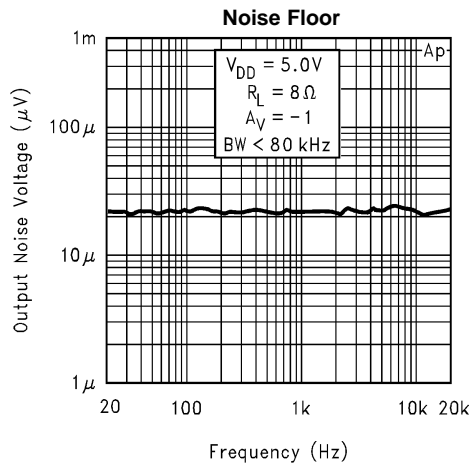


Figure 30.

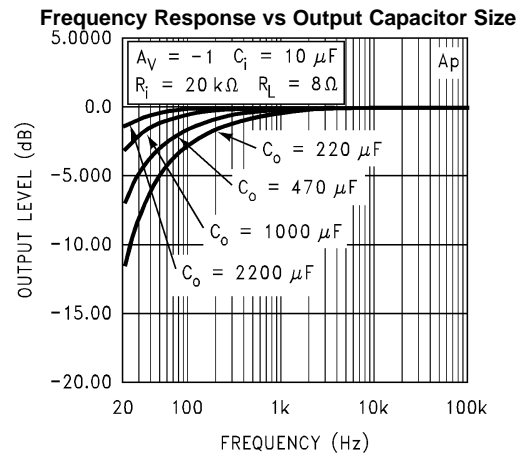


Figure 31.

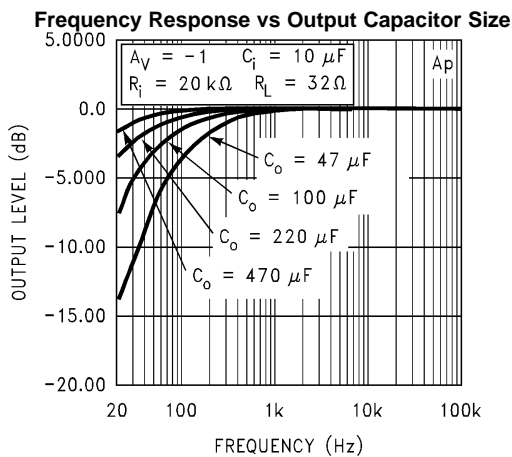


Figure 32.

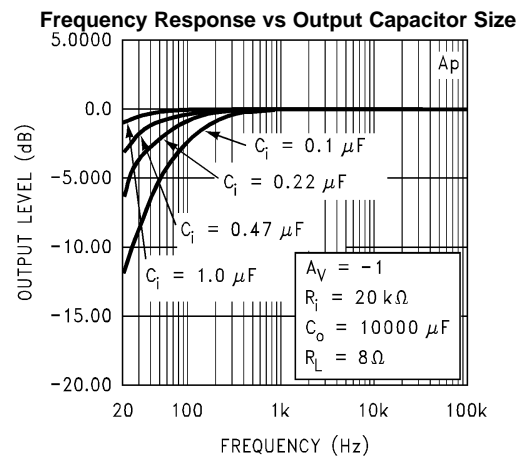
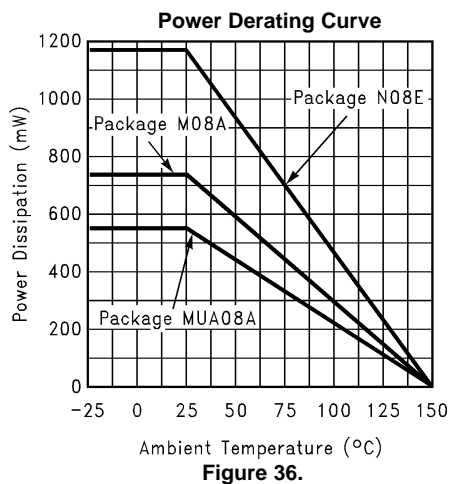
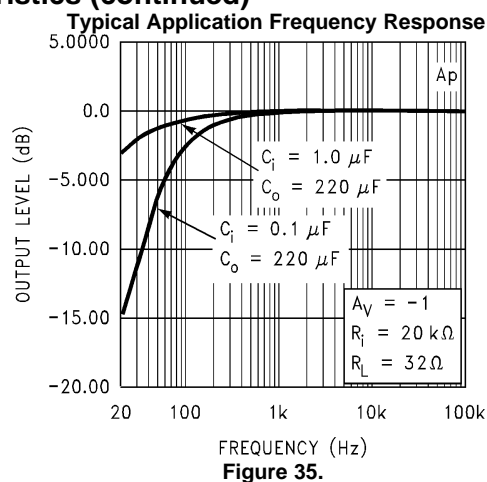
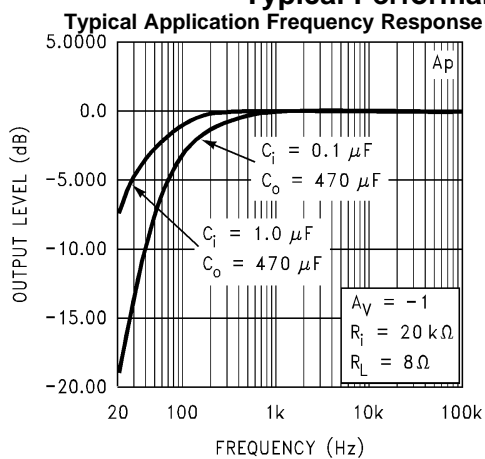


Figure 33.

## Typical Performance Characteristics (continued)



## APPLICATION INFORMATION

### SHUTDOWN FUNCTION

In order to reduce power consumption while not in use, the LM4881 contains a shutdown pin to externally turn off the amplifier's bias circuitry. This shutdown feature turns the amplifier off when a logic high is placed on the shutdown pin. The trigger point between a logic low and logic high level is typically half supply. It is best to switch between ground and supply to provide maximum device performance. By switching the shutdown pin to the  $V_{DD}$ , the LM4881 supply current draw will be minimized in idle mode. While the device will be disabled with shutdown pin voltages less than  $V_{DD}$ , the idle current may be greater than the typical value of 0.7  $\mu$ A. In either case, the shutdown pin should be tied to a definite voltage because leaving the pin floating may result in an unwanted shutdown condition. In many applications, a microcontroller or microprocessor output is used to control the shutdown circuitry which provides a quick, smooth transition into shutdown. Another solution is to use a single-pole, single-throw switch in conjunction with an external pull-up resistor. When the switch is closed, the shutdown pin is connected to ground and enables the amplifier. If the switch is open, then the external pull-up resistor will disable the LM4881. This scheme guarantees that the shutdown pin will not float which will prevent unwanted state changes.

### POWER DISSIPATION

Power dissipation is a major concern when using any power amplifier and must be thoroughly understood to ensure a successful design. Equation 1 states the maximum power dissipation point for a single-ended amplifier operating at a given supply voltage and driving a specified output load.

$$P_{DMAX} = (V_{DD})^2 / (2\pi^2 R_L) \quad (1)$$

Since the LM4881 has two operational amplifiers in one package, the maximum internal power dissipation point is twice that of the number which results from Equation 1. Even with the large internal power dissipation, the LM4881 does not require heat sinking over a large range of ambient temperature. From Equation 1, assuming a 5V power supply and an 8 $\Omega$  load, the maximum power dissipation point is 158 mW per amplifier. Thus the maximum package dissipation point is 317 mW. The maximum power dissipation point obtained must not be greater than the power dissipation that results from Equation 2:

$$P_{DMAX} = (T_{JMAX} - T_A) / \theta_{JA} \quad (2)$$

For package DGK0008A,  $\theta_{JA} = 230^\circ\text{C/W}$ , and for package D0008A,  $\theta_{JA} = 170^\circ\text{C/W}$ , and for package P0008E,  $\theta_{JA} = 107^\circ\text{C/W}$ .  $T_{JMAX} = 150^\circ\text{C}$  for the LM4881. Depending on the ambient temperature,  $T_A$ , of the system surroundings, Equation 2 can be used to find the maximum internal power dissipation supported by the IC packaging. If the result of Equation 1 is greater than that of Equation 2, then either the supply voltage must be decreased, the load impedance increased or  $T_A$  reduced. For the typical application of a 5V power supply, with an 8 $\Omega$  load, the maximum ambient temperature possible without violating the maximum junction temperature is approximately 96 $^\circ\text{C}$  provided that device operation is around the maximum power dissipation point. Power dissipation is a function of output power and thus, if typical operation is not around the maximum power dissipation point, the ambient temperature may be increased accordingly. Refer to the Typical Performance Characteristics curves for power dissipation information for lower output powers.

### POWER SUPPLY BYPASSING

As with any power amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. The capacitor location on both the bypass and power supply pins should be as close to the device as possible. As displayed in the Typical Performance Characteristics section, the effect of a larger half supply bypass capacitor is improved low frequency PSRR due to increased half-supply stability. Typical applications employ a 5V regulator with 10  $\mu$ F and a 0.1  $\mu$ F bypass capacitors which aid in supply stability, but do not eliminate the need for bypassing the supply nodes of the LM4881. The selection of bypass capacitors, especially  $C_B$ , is thus dependent upon desired low frequency PSRR, click and pop performance as explained in Proper Selection of External Components system cost, and size constraints.

### PROPER SELECTION OF EXTERNAL COMPONENTS

Selection of external components when using integrated power amplifiers is critical to optimize device and system performance. While the LM4881 is tolerant of external component combinations, consideration to component values must be used to maximize overall system quality.

The LM4881 is unity gain stable and this gives a designer maximum system flexibility. The LM4881 should be used in low gain configurations to minimize THD+N values, and maximize the signal-to-noise ratio. Low gain configurations require large input signals to obtain a given output power. Input signals equal to or greater than 1 V<sub>rms</sub> are available from sources such as audio codecs. Please refer to the section, [Audio Power Amplifier Design](#), for a more complete explanation of proper gain selection.

Besides gain, one of the major considerations is the closed loop bandwidth of the amplifier. To a large extent, the bandwidth is dictated by the choice of external components shown in [Figure 1](#). Both the input coupling capacitor, C<sub>i</sub>, and the output coupling capacitor, C<sub>o</sub>, form first order high pass filters which limit low frequency response. These values should be chosen based on needed frequency response for a few distinct reasons.

### Selection of Input and Output Capacitor Size

Large input and output capacitors are both expensive and space hungry for portable designs. Clearly a certain sized capacitor is needed to couple in low frequencies without severe attenuation. But in many cases the speakers used in portable systems, whether internal or external, have little ability to reproduce signals below 150 Hz. Thus using large input and output capacitors may not increase system performance.

In addition to system cost and size, click and pop performance is effected by the size of the input coupling capacitor, C<sub>i</sub>. A larger input coupling capacitor requires more charge to reach its quiescent DC voltage (nominally 1/2 V<sub>DD</sub>). This charge comes from the output via the feedback and is apt to create pops upon device enable. Thus, by minimizing the capacitor size based on necessary low frequency response, turn on pops can be minimized.

Besides minimizing the input and output capacitor sizes, careful consideration should be paid to the bypass capacitor value. Bypass capacitor C<sub>B</sub> is the most critical component to minimize turn on pops since it determines how fast the LM4881 turns on. The slower the LM4881's outputs ramp to their quiescent DC voltage (nominally 1/2 V<sub>DD</sub>), the smaller the turn on pop. Thus choosing C<sub>B</sub> equal to 1.0 μF along with a small value of C<sub>i</sub> (in the range of 0.1 μF to 0.39 μF), the shutdown function should be virtually clickless and popless. While the device will function properly, (no oscillations or motorboating), with C<sub>B</sub> equal to 0.1 μF, the device will be much more susceptible to turn on clicks and pops. Thus, a value of C<sub>B</sub> equal to 0.1 μF or larger is recommended in all but the most cost sensitive designs.

## AUDIO POWER AMPLIFIER DESIGN

### Design a Dual 200mW/8Ω Audio Amplifier

Given:

Power Output	200 mW <sub>rms</sub>
Load Impedance	8Ω
Input Level	1 V <sub>rms</sub> (max)
Input Impedance	20 kΩ
Bandwidth	100 Hz–20 kHz ± 0.50 dB

A designer must first determine the needed supply rail to obtain the specified output power. Calculating the required supply rail involves knowing two parameters, V<sub>OPEAK</sub> and also the dropout voltage. The latter is typically 530 mV and can be found from the graphs in the [Typical Performance Characteristics](#). V<sub>OPEAK</sub> can be determined from [Equation 3](#).

$$V_{\text{opeak}} = \sqrt{(2R_L P_O)} \quad (3)$$

For 200 mW of output power into an 8Ω load, the required V<sub>OPEAK</sub> is 1.79 volts. A minimum supply rail of 2.32V results from adding V<sub>OPEAK</sub> and V<sub>OD</sub>. Since 5V is a standard supply voltage in most applications, it is chosen for the supply rail. Extra supply voltage creates headroom that allows the LM4881 to reproduce peaks in excess of 200 mW without clipping the signal. At this time, the designer must make sure that the power supply choice along with the output impedance does not violate the conditions explained in the [Power Dissipation](#) section. Remember that the maximum power dissipation point from [Equation 1](#) must be multiplied by two since there are two independent amplifiers inside the package.

Once the power dissipation equations have been addressed, the required gain can be determined from [Equation 4](#).

$$A_V \geq \sqrt{(P_O R_L)} / (V_{IN}) = V_{orms} / V_{inrms} \quad (4)$$

$$A_V = R_f / R_i \quad (5)$$

From [Equation 4](#), the minimum gain is:  $A_V = 1.26$

Since the desired input impedance was 20 kΩ, and with a gain of 1.26, a value of 27 kΩ is designated for  $R_f$ , assuming 5% tolerance resistors. This combination results in a nominal gain of 1.35. The final design step is to address the bandwidth requirements which must be stated as a pair of –3 dB frequency points. Five times away from a –3 dB point is 0.17 dB down from passband response assuming a single pole roll-off. As stated in the [External Components Description](#) section, both  $R_i$  in conjunction with  $C_i$ , and  $C_o$  with  $R_L$ , create first order highpass filters. Thus to obtain the desired frequency low response of 100 Hz within ±0.5 dB, both poles must be taken into consideration. The combination of two single order filters at the same frequency forms a second order response. This results in a signal which is down 0.34 dB at five times away from the single order filter –3 dB point. Thus, a frequency of 20 Hz is used in the following equations to ensure that the response is better than 0.5 dB down at 100 Hz.

$$C_i \geq 1 / (2\pi * 20 \text{ k}\Omega * 20 \text{ Hz}) = 0.397 \text{ }\mu\text{F}; \text{ use } 0.39 \text{ }\mu\text{F}. \quad (6)$$

$$C_o \geq 1 / (2\pi * 8\Omega * 20 \text{ Hz}) = 995 \text{ }\mu\text{F}; \text{ use } 1000 \text{ }\mu\text{F}. \quad (7)$$

The high frequency pole is determined by the product of the desired high frequency pole,  $f_H$ , and the closed-loop gain,  $A_V$ . With a closed-loop gain of 1.35 and  $f_H = 100 \text{ kHz}$ , the resulting GBWP = 135 kHz which is much smaller than the LM4881 GBWP of 18 MHz. This figure displays that if a designer has a need to design an amplifier with a higher gain, the LM4881 can still be used without running into bandwidth limitations.

## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

### Products

Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>
OMAP Applications Processors	<a href="http://www.ti.com/omap">www.ti.com/omap</a>
Wireless Connectivity	<a href="http://www.ti.com/wirelessconnectivity">www.ti.com/wirelessconnectivity</a>

### Applications

Automotive and Transportation	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Energy and Lighting	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
Space, Avionics and Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>

### TI E2E Community

[e2e.ti.com](http://e2e.ti.com)